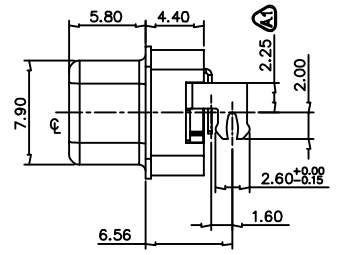
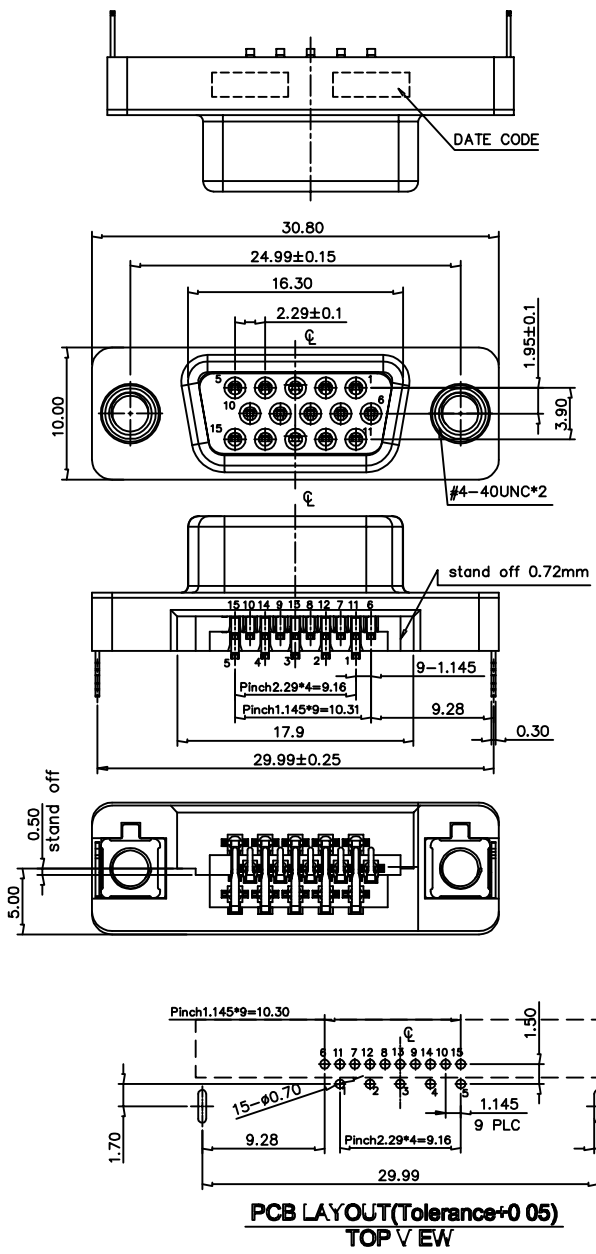


1 2 3 4 5 6 7

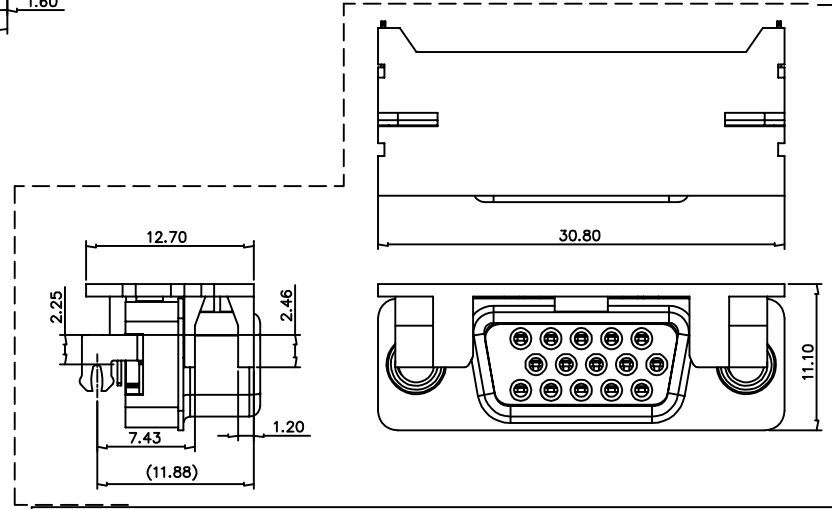
A
B
C
D
E



Remark:
1. MATERIAL:
1.1 Housing:LCP+30MG.F UL94V 0, Color:black.
1.2 Contact:COPPER ALLOY, GOLD PLATING
ON CONTACT AREA, 80u" Matte MIN TIN PLATING ON
SOLDERTAILS, 50u" MIN NICKEL UNDERPLATING OVER ALL.
1.3 Shell:SPCC, 50u" MIN NICKEL PLATING.
1.4 BOARD LOCK:SPCC, 50u" MIN. Matte TIN PLATING.
1.5 RIVET:COPPER ALLOY, NICKEL PLATING.

20343-T MX X X

- S1:半金穿隔 5 u"
 - S2:半金穿隔 flash
 - S3:半金穿隔 10 u"
 - S4:半金穿隔 15 u"
 - S5:半金穿隔 30 u"
- L: 袋带包装
 - A: 吸盘盒包装
 - Z: 黑色
 - 4: 660C 蓝色



DIMENSIONS
TOLERANCE
METRIC
.0= ±.38
.00= ±.25
.000= ±.15
.0000= ±.
ANG.= ±2°

尚益科技有限公司
JMSCONN TECHNOLOGY CO., LTD.

PROJ	SCALE : F DO NOT SCALE DWG	MOLD NO 20343-T
APP		MODEL
CHK		FILE NO
DGN		REV. X1
DRW	HSIEH	UNIT MM
	2013.09.22	SHT 1 OF 1
		SIZE A4

1 2 3 4 5 6 7